

Sheet Resistance Measuring System



WS-3000

- High reliable measurement with high performance tester and 4-point probe head, and stable wafer loading mechanism
- Automatic probe head selection (exchanger) among four kinds of probe with rotary mechanism
- Dual mode enables highly accurate measurement (edge 1mm capability)
- The measurement capability 3nm~ 1,500nm for thin films
- Range : 1.0m Ω /□~10M Ω /□ (or 1.0G Ω /□ with option)
- 49 points mapping / 60 seconds (300mm wafer)
- Tact time : less than 120 seconds / wafer (includes load~ 49 points meas.~ unload)
- FOUF (one or two ports) and GEM/SECS network compatible
- FFU (ULPA) mini-environment
- Standard mapping (2-D, 3-D) measurement up to 1,225 points and optional user programmable mapping
- 200mm SMIF/AM3000 compatible with option
- Internal resistance accuracy : $\pm 0.1\%$ (1 Ω ~ 1M Ω)
- Repeatability : CV $\leq 0.17\%$

APPLICATIONS

Semiconductor process (epitaxial, diffused, ion-implanted, poly silicon), metal layers and Standard silicon wafers

DIMENSIONS

One four version : 2,250 (W) \times 700 (D) \times 1,800 (H) mm,
600kg

Two fousps version : 1,390 (W) \times 1,800 (D) \times 1,800 (H) mm,
800kg

UTILITIES

Power supply : *Select from 100~240V, 50/60Hz, 3kVA

Vacuum : -86kPa

CDA (or N₂) : 0.7MPa (7.0kgf/cm²) with air regulator



* Automatic probe exchanger among 4-kinds of probe head

